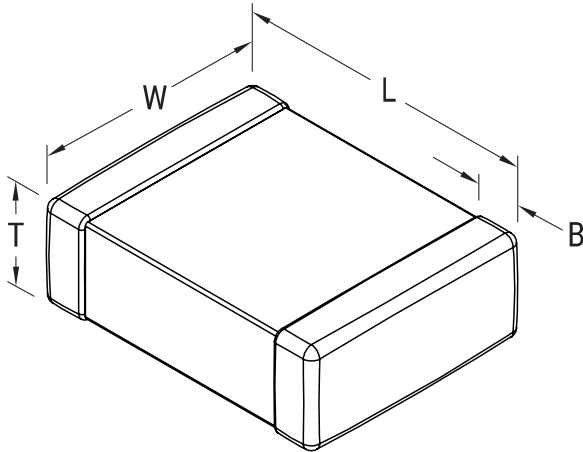


## CBR06C849B1GAC

CBR-SMD RF COG, Ceramic, 8.4 pF,  $\pm 0.1$  pF, 100 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0603



Click [here](#) for the 3D model.

### General Information

Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	5.29 mg
Notes	Solder Wave or Solder Reflow.
Shelf Life	78 Weeks
MSL	1

### Dimensions

Chip Size	0603
L	1.6mm $\pm 0.1$ mm
W	0.8mm $\pm 0.1$ mm
T	0.8mm $\pm 0.07$ mm
B	0.4mm $\pm 0.15$ mm

### Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

### Specifications

Capacitance	8.4 pF
Tolerance	$\pm 0.1$ pF
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.176%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	568

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